



Product/Process Change Notice - PCN 20_0165 Rev. A

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly Transfer of Select PBGA Products to ASE Chungli (AET)

Publication Date: 14-Jul-2021

Effectivity Date: 16-Oct-2021 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Update Qualification Plan Summaries for 23x23 BGA and 27x27 BGA.

Description Of Change:

Assembly site for selected (23x23) and (27x27) PBGA parts are moving from STATS ChipPAC Singapore (STA) to ASE Chungli Taiwan (AET).

Change in Mold compound from Sumitomo G770 to Hitachi CEL-9750.

Existing qualified BOM in SK3 will be used.

Reason For Change:

STATS ChipPAC, Singapore (STA) issued a discontinuance notice to ADI to close their wirebonded products assembly by Dec 31, 2020.

ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, materials, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability:

No impact on form, fit and function or reliability.

Product Identification *(this section will describe how to identify the changed material)*

Parts assembled at AET will be identified by Assembly Lot number and Date Code.

Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_20_0165_Rev_A_001573_Qual Plan Summary for 23x23 BGA at ASECL Taiwan.pdf

Attachment 2: Type: Qualification Plan

ADI_PCN_20_0165_Rev_A_001572_Qual Plan Summary for 27x27 BGA at ASECL Taiwan.pdf

Attachment 3: Type: Detailed Change Description

ADI_PCN_20_0165_Rev_A_Material Set_STA to AET PBGA Transfer.pdf

Attachment 4: Type: Package Outline Drawing

ADI_PCN_20_0165_Rev_A_STA to AET PBGA Transfer Package Outline Drawing Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (9)				
ADSP-21060L / ADSP-21060LABZ-160	ADSP-21061L / ADSP-21061LKBZ-160	ADSP-21160M / ADSP-21160MKBZ-80	ADSP-21160N / ADSP-21160NCBZ-100	ADSP-BF561 / ADSP-BF561SBBZ500
ADSP-BF561 / ADSP-BF561SBBZ600	ADSP-BF561 / ADSP-BF561SKBZ600	ADSP-TS101S / ADSP-TS101SAB1Z000	ADSP-TS101S / ADSP-TS101SAB1Z100	

Appendix B - Revision History			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	26-Aug-2020	28-Nov-2020	Initial Release.
Rev. A	14-Jul-2021	16-Oct-2021	Update Qualification Plan Summaries for 23x23 BGA and 27x27 BGA.

Analog Devices, Inc.

DocId:8593 Parent DocId:None Layout Rev:7